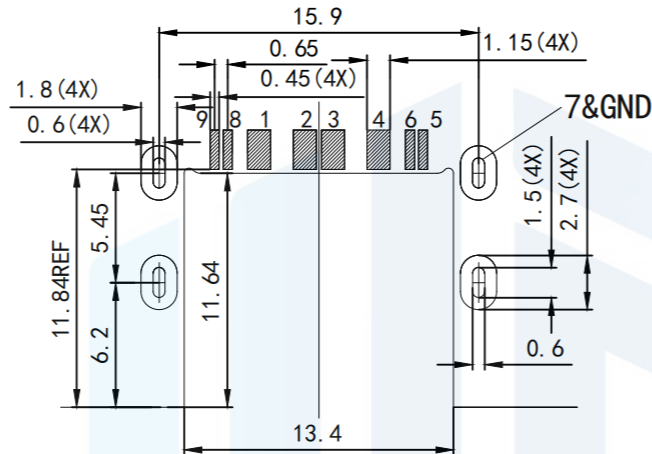
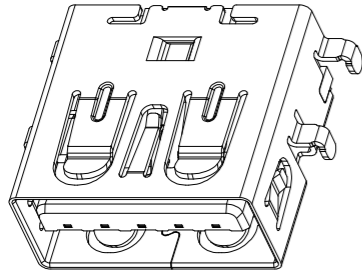
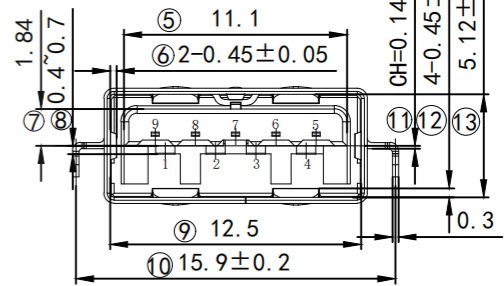
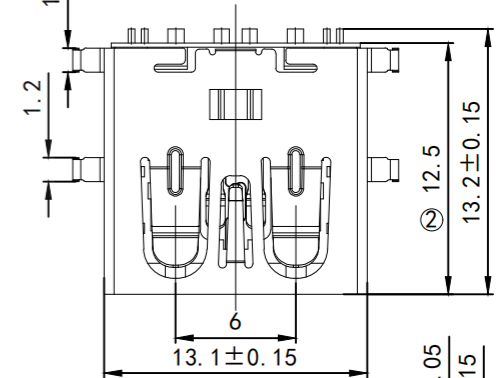


RoHS2.0
Compliant



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



NOTE:

1. MATERIAL:

- 1.1 INSULATOR:LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: C5191-EH.
- 1.3 CONTACT 5~9PIN: C5191-EH.
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

2.1 CONTACT:

CONTACT AREA: GOLD PLATING.
SOLDER AREA: 100u" Min MATTE TIN PLATING.
UNDER PLATE: 50u" Min NICKEL PLATING.

2.2 SHELL:50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

3.1 ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 30mΩ MAXIMUM
CONTACT CURRENT RATING: 3A
DIELECTRIC WITHSTANDING VOLTAGE: 500 V R. M. S.
INSULATION RESISTANCE: 100 MEGOHMS MIN
OPERATING TEMPERATURE: -25° C ~ +85° C

3.2 MECHANICAL:

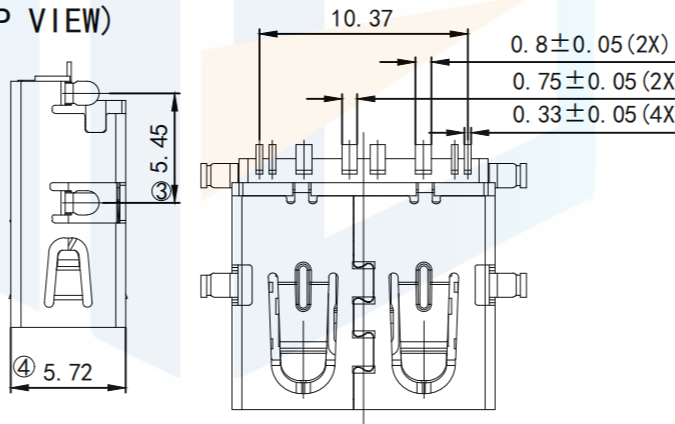
MATING FORCE: 3.57KG Max.
UNMATING FORCE: 1.02KG Min.

4. PART MUST COMPLY ROHS SPECIFICATION

5. WAVE SOLDER: THE CONNECTOR SHALL BE MOUNTED ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL BE 260±5 ° C AND IMMERSION DURATION 5 SECONDS.

TOLERANCE: ±0.05, RECOMMENDED PCB LAYOUT

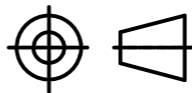
(TOP VIEW)



TOLERANCE

X. XXX	±0.05
X. XX	±0.15
X. X	±0.20
X.	±0.30
ANGLE	±5.0°

PROTECTON



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TITLE:

USB3.1 A/F 沉板3.0直边
4定位脚外移(10GB)

PART NO:USB3.1-V177

DRAWING NO:13.1*12.5*5.72

DRAWN:

DATE: 18-10-08

UNIT:
mm

CHECKED:

DATE: 18-10-08

SCALE:
FULL

APPROVED:

DATE: 18-10-08

SIZE:
A4